Power devices / Cooling plates

Analysing voiding and soldered area of assembled power devices and cooling plates. Special solder-level separation technique for multi-layer soldering applications (hybrid-power components).

**Inspection coverage (extract):**

- Voiding [%]
- Voiding (area)
- Void-separation for multi-layer (i.e. for chip-layer and substrate layer)
- Soldering area

Requires high power setup and 16 Bit detector technology for heavy cooling plates. By using the MatriX SFT™ Technology - inhomogeneous backgrounds and disturbing structures are eliminated, thus assuring a correct void calculation.

**Product Family**

![X series](image1)

![X# series](image2)

![XT series](image3)